



EPOXY ADHESIVE

K-POXY 831



K-POXY 831 is a two-component epoxy resin adhesive that cures at normal and low temperatures. It is easy to use, cures quickly, provides strong adhesion and can be cured by heating. It is specially designed for electronic components potting, bonding metals, electronic products, hard materials bonding and mold infusion, as well as insulating and moisture-proof potting, providing a protective cover.

- EXCELLENT ADHESION
- HIGH SHEAR STRENGTH
- TEMPERATURE RESISTANCE
- US FDA 21 CFR – FOOD GRADE

CHEMICAL BASIS	Epoxy
WORK TIME	30 min
COLOR	Transparent
HARDNESS	65 D
VISCOSITY	10 000 mPa.s

PROPERTIES	RESIN (A)	HARDENER (B)
Mix ratio (weight)	100	100
Color	Transparent	Transparent
Viscosity (25°C)	8.000 – 12.000 mPa.s	5.500 – 8.500 mPa.s
Specific density	1.15	1.05
Work time	30min	
Curing conditions	25°C x 2-3hours or 55°C x 5min (2g)	
Shore D hardness	65D	
Elongation (%)	25	
Tensile strength (MPa)	13	
Dielectric strength (kV/mm)	22	
Bending strength (kg/mm ²)	25	
Volume resistivity (ohm.cm)	1 x 10 ¹⁵	
Surface resistance (ohm)	5 x 10 ¹⁵	
Thermal conductivity (W/m.K)	0.56	
Dielectric loss (1 KHz)	0.42	
Heat distortion temperature (°C)	140	
Water absorption (%)	<0.15	
Lap shear strength – Stainless Steel (MPa)	9	

THE BONDING KEY !



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SURFACE PREPARATION

To obtain maximum adhesive performance from the **K-POXY 831** is essential that all substrates are clean, dry and free from surface contamination such as oil or grease.

MIXING OF THE PRODUCT AND STRENGTH

Mix **K-POXY 831** from part A to part B in equal quantities. Mix the two parts thoroughly for optimal performance. Epoxy can be dispensed, metered, mixed and applied directly to the bonding surface.

APPLICATION OF THE PRODUCT

After mixing, the **K-POXY 831** must be applied directly to the surfaces to be bonded. If an insert is to be glued into a socket or bend, the surfaces to be fixed lightly rotating the units will eliminate any air entrapment and completely wet both surfaces. surfaces.

Edge-to-edge collages must be supported 5mm adhesive thickness will provide maximum bond strength.

NOTE

The information, and particularly the recommendations regarding the application and the KEOL products, are given to you in good faith and are based on current knowledge and experience of the products having been properly stored, handled and applied under normal conditions.

KEOL cannot take responsibility for the results obtained by others since we have no control over their method.

It is up to the user to determine the suitability of the products for the specific application for any method. production costs mentioned in this document. Also, it is up to the user to adopt the necessary precautions as recommended for the protection of the establishment and the people against any kind of risks which could arise during the handling and the use of the products.

KEOL cannot assume all the guarantees mentioned or implied, including guarantees of market value. or compliance for a specific reason, arising from sales or use of KEOL products. KEOL cannot assume liability for incidental consequences or damages of any kind, including lost profits.

Users should always refer to the most recent edition of the technical data sheet for the product concerned. Copies of this document will be provided upon request.

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